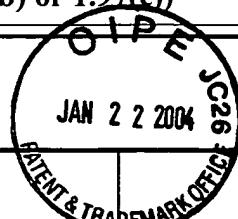


**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
 (Under 37 CFR 1.97(b) or 1.97(c))

Docket No.  
 AM-5209-D2

In Re Application: Ling CHEN et al.



Serial No.  
 10/693,775

Filing Date  
 October 24, 2003

Examiner  
 unknown

Group Art Unit  
 unknown

Tantalum Barrier Layer for Copper Metallization

**Payment of Fee**

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- A check in the amount of \_\_\_\_\_ is attached.
- The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 50-0636 as described below. A duplicate copy of this sheet is enclosed.
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Dated: January 13, 2004

Charles S. Guenzer, Reg. No. 30,640

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Applied Materials, Inc.

Patent/Legal Department

P.O. Box 450A

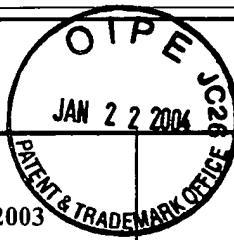
Santa Clara, CA 95052

CC:

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Title: Tantalum Barrier Layer for Copper Metallization

Address to:

Assistant Commissioner for Patents  
Washington, D.C. 20231

**37 CFR 1.97(b)**

1.  The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

**37 CFR 1.97(c)**

2.  The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

the statement specified in 37 CFR 1.97(e);

**OR**

the fee set forth in 37 CFR 1.17(p).

U.S. Department of Commerce, Patent and Trademark Office				Docket No.: AM-5209.D2				
				Serial No.: 10/693,775				
LIST OF RELEVANT ART CITED BY APPLICANT <i>(Use several sheets if necessary)</i>				Applicant: Ling Chen et al.				
				Filing Date: October 24, 2003				
				Group: Unknown				
U.S. PATENT DOCUMENTS								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	5,770,519	06/23/98	Klein et al.	438	639		
	AB	5,846,332	12/08/98	Zhao et al.	118	728		
	AC	5,933,753	08/03/99	Simon et al.	438	629		
	AD	5,985,762	11/16/99	Geffken et al.	438	687		
	AE	6,106,625	08/22/00	Koai et al.	118	715		
	AF	6,265,313	07/24/01	Huang et al.	438	687		
	AG	6,277,249	08/21/01	Gopalraja et al.	204	192.12		
	AH	6,284,657	09/04/01	Chooi et al.	438	687		
	AI	6,287,977	09/11/01	Hashim et al.	438	722		
	AJ	6,294,458	09/25/01	Zhang et al.	438	627		
	AK	6,306,732	10/23/01	Brown	438	468		
FOREIGN PATENT DOCUMENTS (Translation)								
		Document Number	Date	Country	Class	Subclass	Yes	No
	AL	XP-002223600	5/11/2000	Japan			Abstract	
	AM	2000-323571	11/24/00	Japan			Abstract	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
	AR	Yamagihshi et al., "TEM/SEM Investigation and Electrical Evaluation of a Bottomless 1-PVS Ta(N) Barrier in a Dual Mask", <i>Advanced Metallization Conference 2000, Proceedings of the Conference 2000, Advanced Metallization Conference 2000, Proceedings of the Conference, San Diego, CA, USA, October 2-5, 2000, 279-285 pp.</i>						
	AS							
	AT							
Examiner			Date Considered					
<p><b>*EXAMINER:</b> Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.</p>								